



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Hall et al.

Serial No.: 10/785,122

Filed: February 24, 2004

For: UNDERFILLED, ENCAPSULATED
SEMICONDUCTOR DIE ASSEMBLIES
AND METHODS OF FABRICATION

Confirmation No.: Unknown

Examiner: Unknown

Group Art Unit: Unknown

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CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

April 6, 2004
Date

Signature

Deidra J. Pfeil
Name (Type/Print)

PRELIMINARY AMENDMENT

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please revise the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Amendments to the Drawings appear on page 9 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

Remarks begin on page 10 of this paper.

An **Appendix** including amended drawing figures is attached following page 10 of this paper.